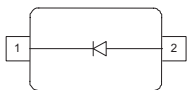


Silicon PIN Diodes

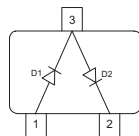
- PIN diode for high speed switching of RF signals
- Very low forward resistance (low insertion loss)
- Very low capacitance (high isolation)
- For frequencies up to 3GHz
- Pb-free (RoHS compliant) package
- Qualified according AEC Q101¹⁾



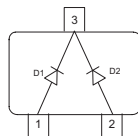
BAR63-02..
BAR63-03W



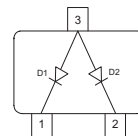
BAR63-04
BAR63-04W



BAR63-05
BAR63-05W



BAR63-06
BAR63-06W



Type	Package	Configuration	L_s (nH)	Marking
BAR63-02L*	TSLP-2-1	single, leadless	0.4	G
BAR63-02V	SC79	single	0.6	G
BAR63-02W	SCD80	single	0.6	GG
BAR63-03W	SOD323	single	1.8	white G
BAR63-04	SOT23	series	1.8	G4s
BAR63-04W	SOT323	series	1.4	G4s
BAR63-05	SOT23	common cathode	1.8	G5s
BAR63-05W	SOT323	common cathode	1.4	G5s
BAR63-06	SOT23	common anode	1.8	G6s
BAR63-06W	SOT323	common anode	1.4	G6s

¹⁾BAR63-02L is not qualified according AEC Q101

Maximum Ratings at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Value	Unit
Diode reverse voltage	V_R	50	V
Forward current	I_F	100	mA
Total power dissipation BAR63-02L, $T_S \leq 118^\circ\text{C}$ BAR63-02V, -02W, BAR63-03W, $T_S \leq 115^\circ\text{C}$ BAR63-04...BAR63-06, $T_S \leq 55^\circ\text{C}$ BAR63-04S, $T_S \leq 115^\circ\text{C}$ BAR63-04W...BAR63-06W, $T_S \leq 105^\circ\text{C}$	P_{tot}	250 250 250 250 250	mW
Junction temperature	T_j	150	$^\circ\text{C}$
Operating temperature range	T_{op}	-55 ... 125	
Storage temperature	T_{stg}	-55 ... 150	

Thermal Resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾ BAR63-02L BAR63-02V, BAR63-02W BAR63-03W BAR63-04...BAR63-06 BAR63-04S BAR63-04W...BAR63-06W	R_{thJS}	≤ 125 ≤ 140 ≤ 155 ≤ 380 ≤ 180 ≤ 180	K/W

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	

DC Characteristics

Breakdown voltage $I_{(\text{BR})} = 5 \mu\text{A}$	$V_{(\text{BR})}$	50	-	-	V
Reverse current $V_R = 35 \text{ V}$	I_R	-	-	10	nA
Forward voltage $I_F = 100 \text{ mA}$	V_F	-	0.95	1.2	V

¹⁾For calculation of R_{thJA} please refer to the Technical Information

Electrical Characteristics at $T_A = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Values			Unit	
		min.	typ.	max.		
AC Characteristics						
Diode capacitance $V_R = 5\text{ V}$, $f = 1\text{ MHz}$ $V_R = 0\text{ V}$, 100 MHz ... 1.8 GHz	C_T	- -	0.21 0.3	0.3 -	pF	
Reverse parallel resistance $V_R = 0\text{ V}$, $f = 100\text{ MHz}$ $V_R = 0\text{ V}$, $f = 1\text{ GHz}$ $V_R = 0\text{ V}$, $f = 1.8\text{ GHz}$	R_P	- - -	500 15 5	- - -	kΩ	
Forward resistance $I_F = 5\text{ mA}$, $f = 100\text{ MHz}$ $I_F = 10\text{ mA}$, $f = 100\text{ MHz}$	r_f	- -	1.2 1	2 -	Ω	
Charge carrier life time $I_F = 10\text{ mA}$, $I_R = 6\text{ mA}$, measured at $I_R = 3\text{ mA}$, $R_L = 100\text{ }\Omega$	τ_{rr}	-	75	-	ns	
I-region width	W_I	-	4.5	-	μm	
Insertion loss ¹⁾ $I_F = 1\text{ mA}$, $f = 1.8\text{ GHz}$ $I_F = 5\text{ mA}$, $f = 1.8\text{ GHz}$ $I_F = 10\text{ mA}$, $f = 1.8\text{ GHz}$	I_L	- - -	0.15 0.11 0.1	- - -	dB	
Isolation ¹⁾ $V_R = 0\text{ V}$, $f = 0.9\text{ GHz}$ $V_R = 0\text{ V}$, $f = 1.8\text{ GHz}$ $V_R = 0\text{ V}$, $f = 2.45\text{ GHz}$	I_{SO}	- - -	17.9 12.3 10	- - -		
Series inductance	L_S	-	-	-		

¹⁾BAR63-02L in series configuration, $Z = 50\Omega$

Diode capacitance $C_T = f(V_R)$

$f = 1\text{MHz} - 1.8\text{GHz}$



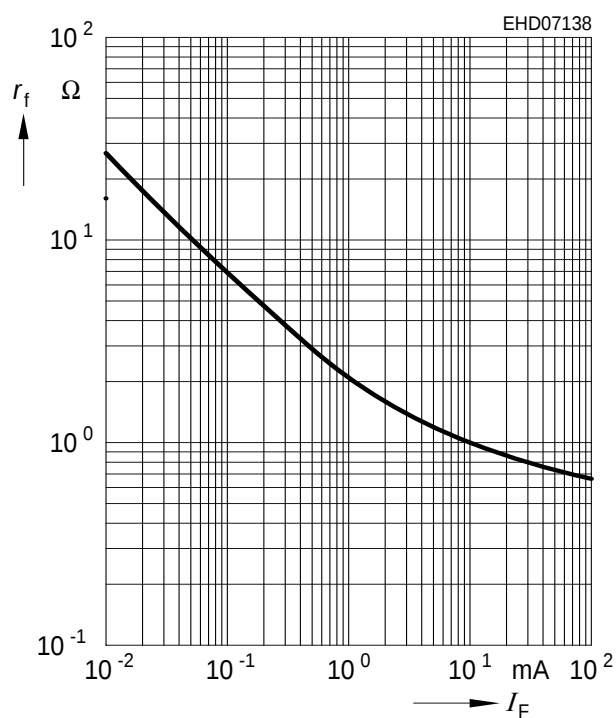
Reverse parallel resistance $R_P = f(V_R)$

$f = \text{Parameter}$



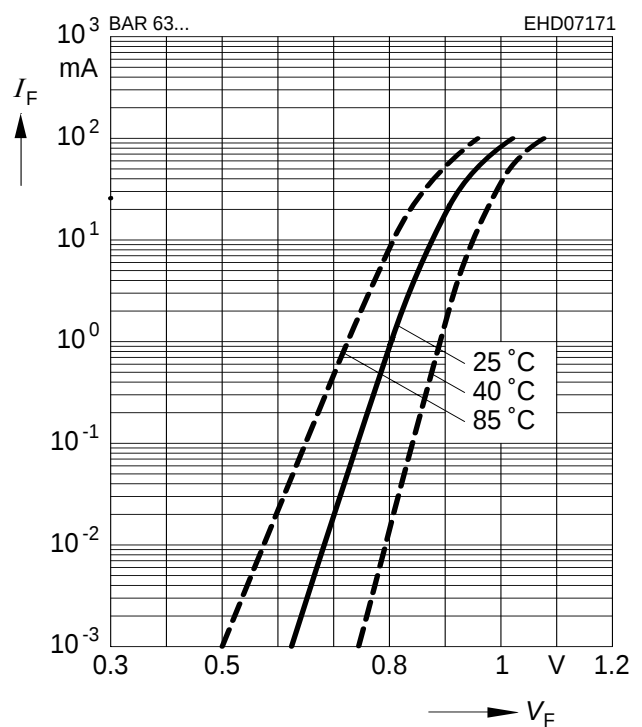
Forward resistance $r_f = f(I_F)$

$f = 100\text{MHz}$



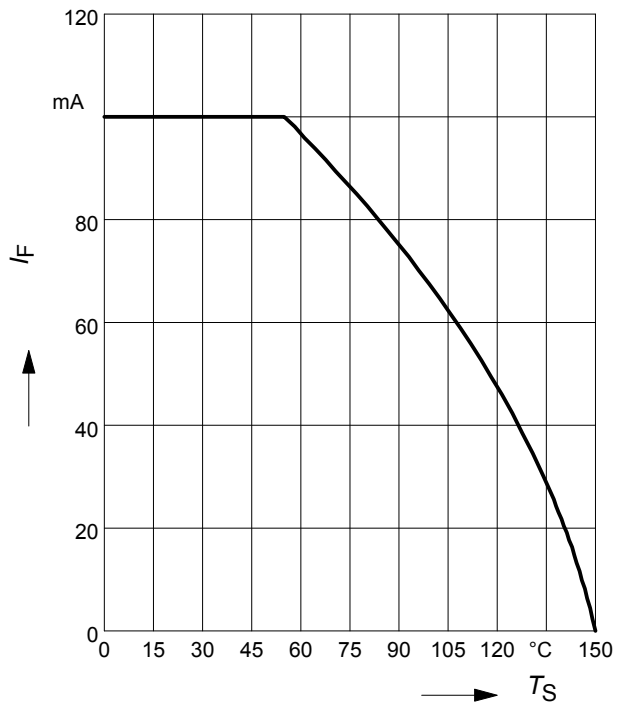
Forward current $I_F = f(V_F)$

$T_A = \text{Parameter}$



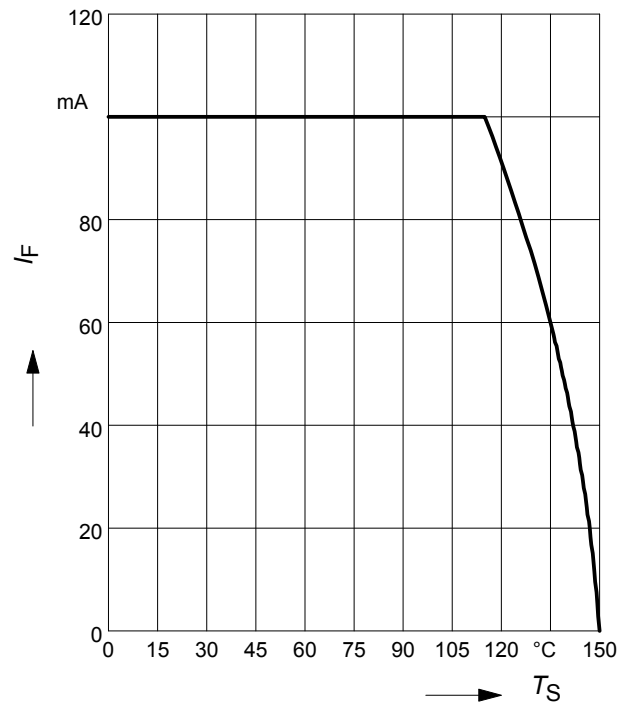
Forward current $I_F = f(T_S)$

BAR63-04...BAR63-06



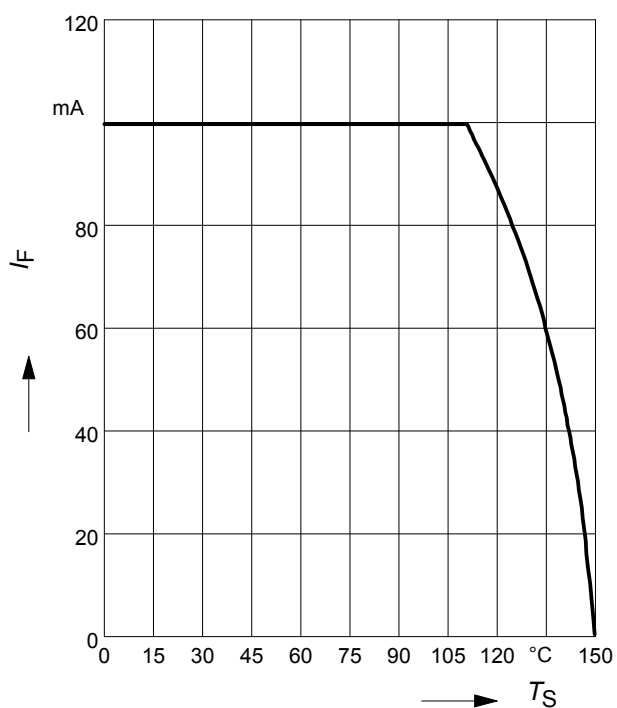
Forward current $I_F = f(T_S)$

BAR63-02V, BAR63-02W



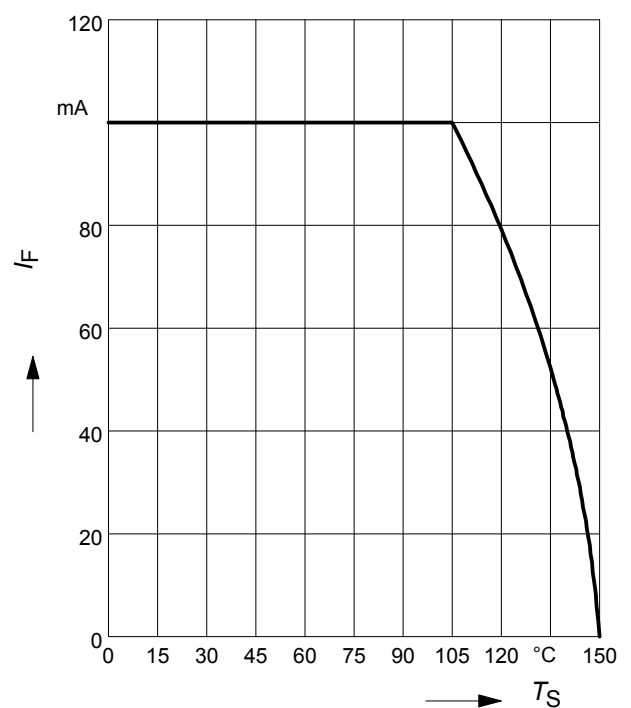
Forward current $I_F = f(T_S)$

BAR63-03W



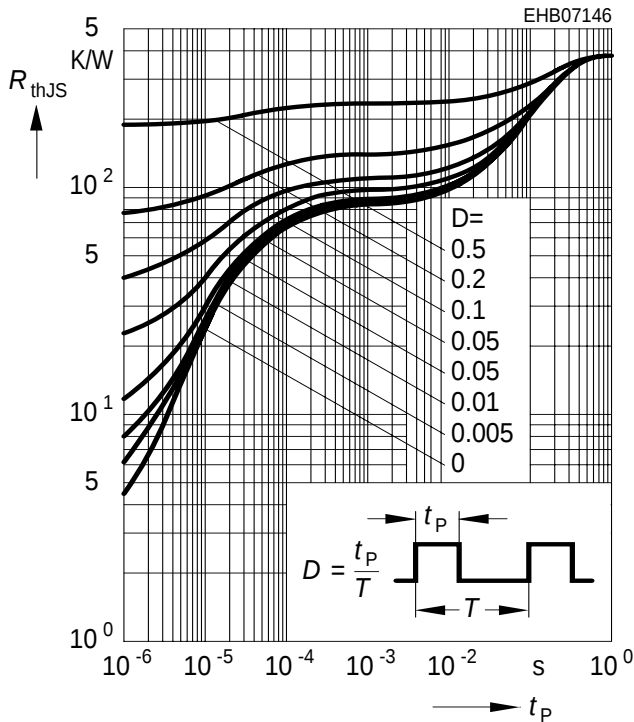
Forward current $I_F = f(T_S)$

BAR63-04W...BAR63-06W



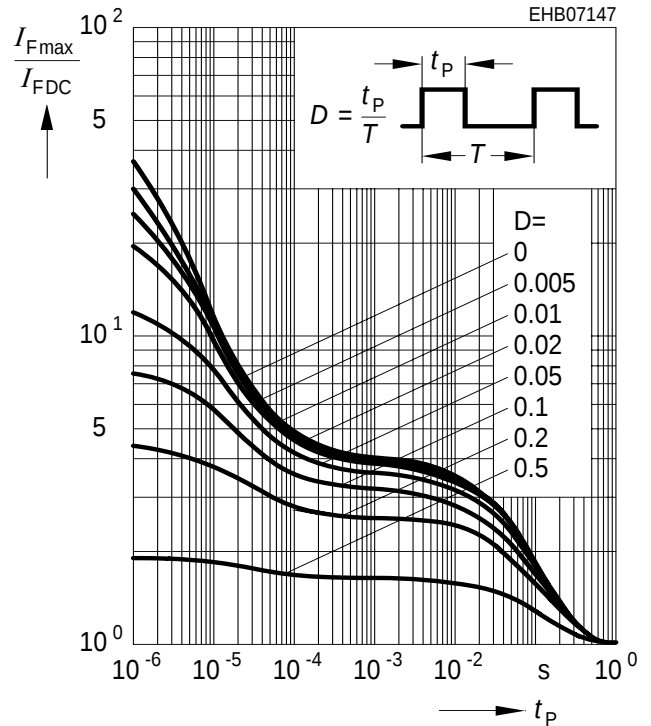
Permissible Puls Load $R_{thJS} = f(t_p)$

BAR63-04...BAR63-06

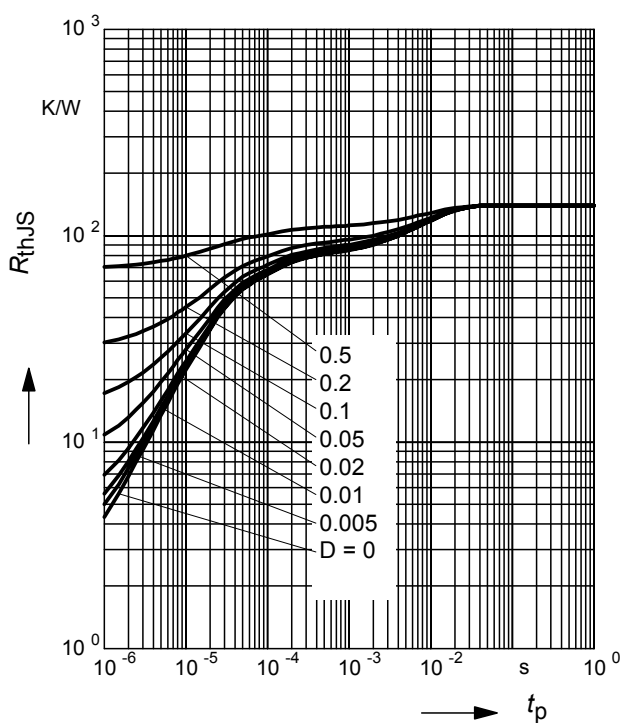

Permissible Pulse Load

$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAR63-04...BAR63-06

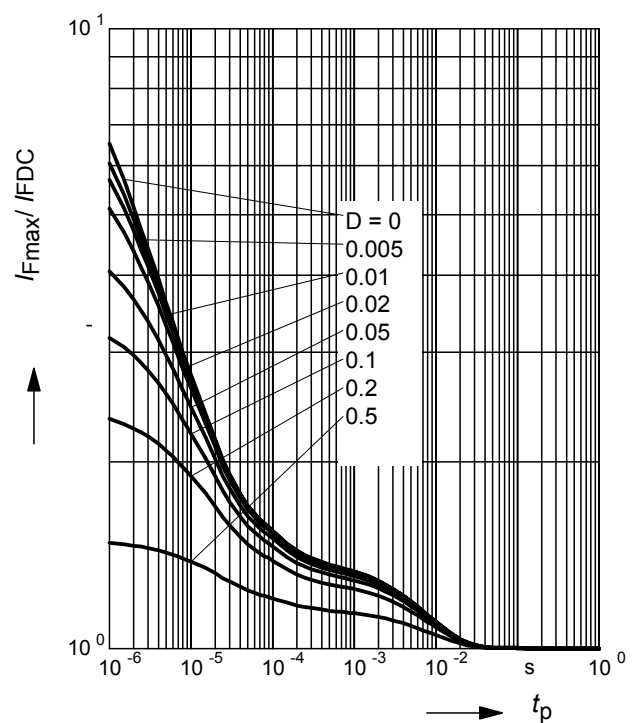

Permissible Puls Load $R_{thJS} = f(t_p)$

BAR63-02V, BAR63-02W


Permissible Pulse Load

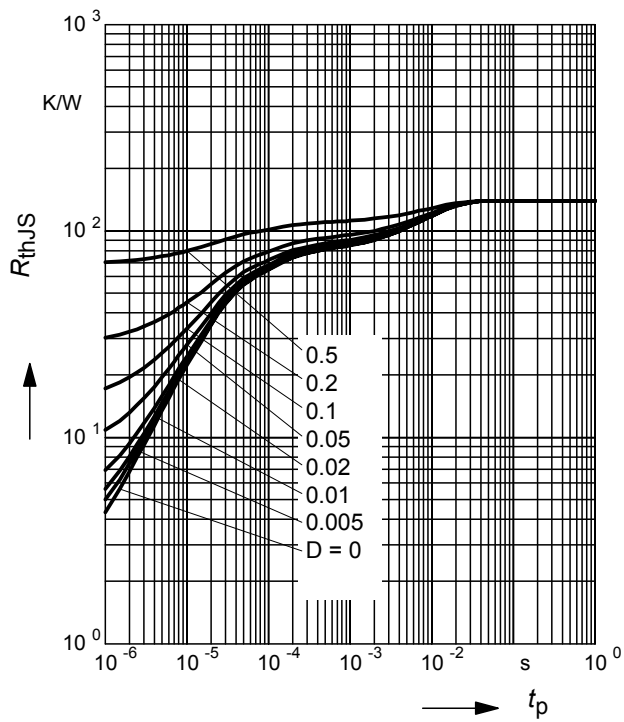
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAR63-02V, BAR63-02W



Permissible Puls Load $R_{thJS} = f(t_p)$

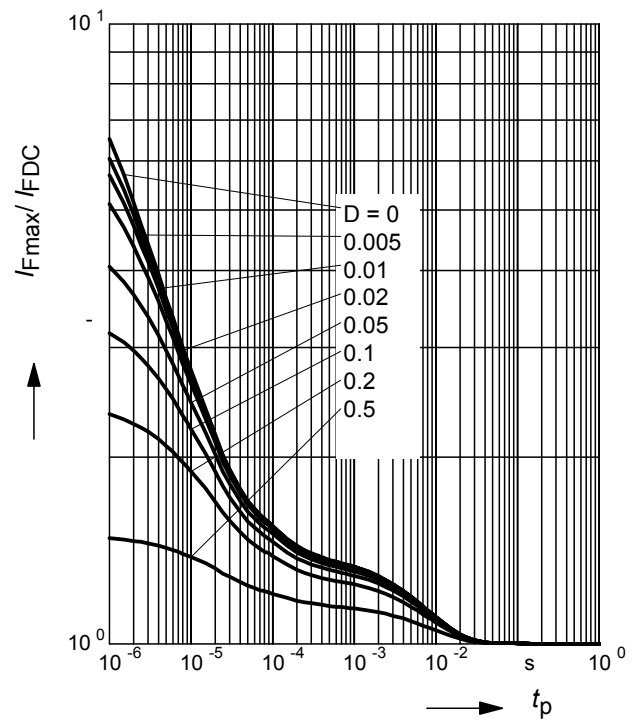
BAR63-03W



Permissible Pulse Load

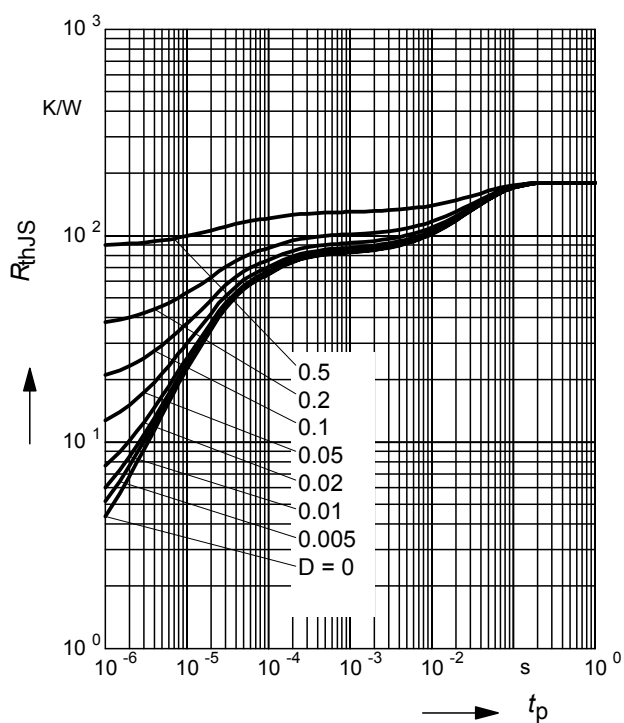
$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAR63-03W



Permissible Puls Load $R_{thJS} = f(t_p)$

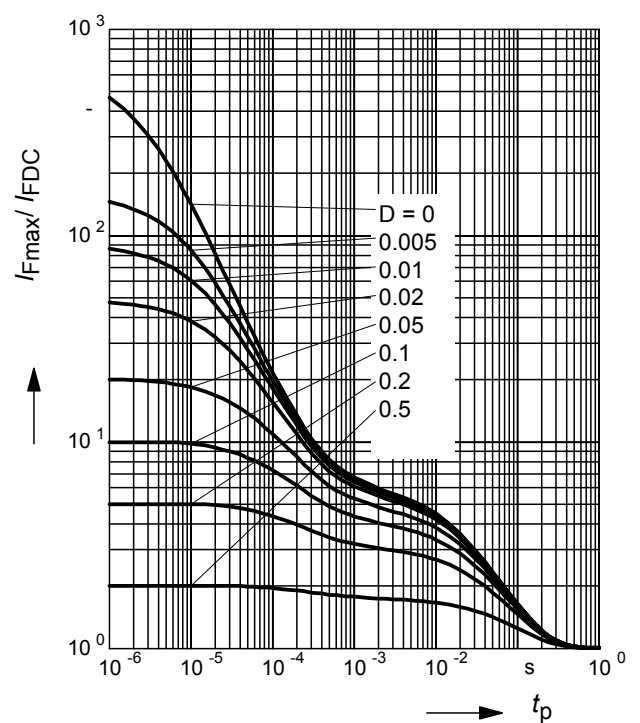
BAR63-04W...BAR63-06W



Permissible Pulse Load

$$I_{Fmax}/I_{FDC} = f(t_p)$$

BAR63-04W...BAR63-06W



Insertion loss $I_L = -|S_{21}|^2 = f(f)$

I_F = Parameter

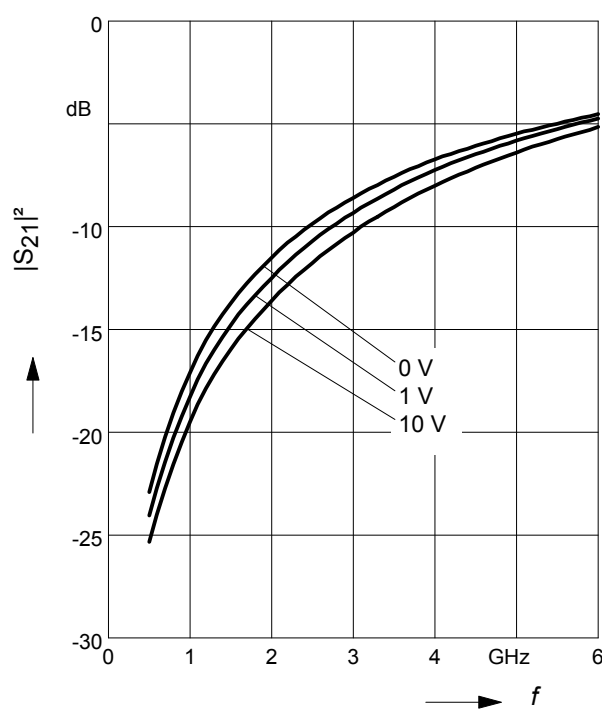
BAR63-02L in series configuration, $Z = 50\Omega$



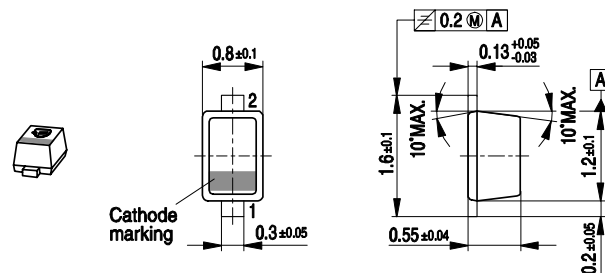
Isolation $I_{SO} = -|S_{21}|^2 = f(f)$

V_R = Parameter

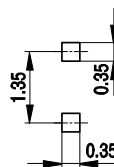
BAR63-02L in series configuration, $Z = 50\Omega$



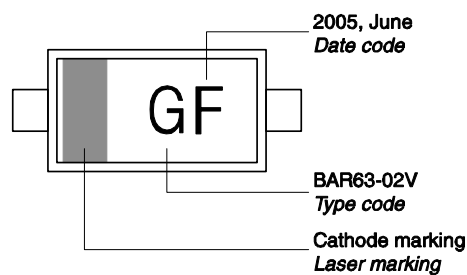
Package Outline



Foot Print

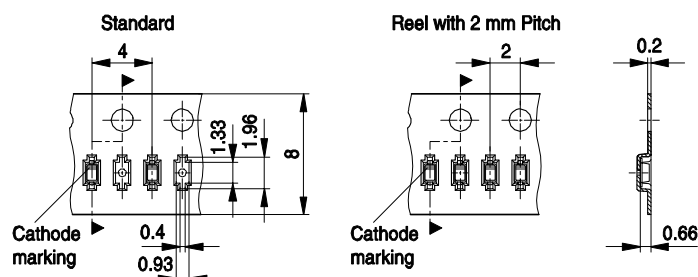


Marking Layout (Example)



Standard Packing

Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Reel $\varnothing 180$ mm = 8.000 Pieces/Reel (2 mm Pitch)
 Reel $\varnothing 330$ mm = 10.000 Pieces/Reel



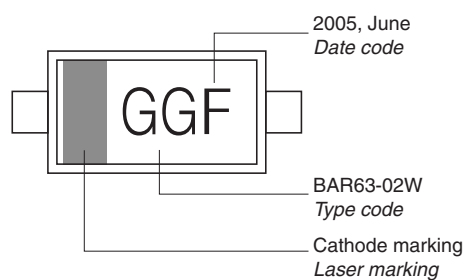
Package Outline



Foot Print



Marking Layout (Example)



Standard Packing

Reel ø180 mm = 3.000 Pieces/Reel
 Reel ø180 mm = 8.000 Pieces/Reel (2 mm Pitch)
 Reel ø330 mm = 10.000 Pieces/Reel



Date Code marking for discrete packages with one digit (SCD80, SC79, SC75¹⁾) CES-Code

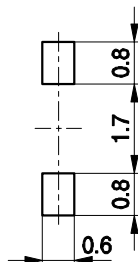
Month	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014
01	a	p	A	P	a	p	A	P	a	p	A	P
02	b	q	B	Q	b	q	B	Q	b	q	B	Q
03	c	r	C	R	c	r	C	R	c	r	C	R
04	d	s	D	S	d	s	D	S	d	s	D	S
05	e	t	E	T	e	t	E	T	e	t	E	T
06	f	u	F	U	f	u	F	U	f	u	F	U
07	g	v	G	V	g	v	G	V	g	v	G	V
08	h	x	H	X	h	x	H	X	h	x	H	X
09	j	y	J	Y	j	y	J	Y	j	y	J	Y
10	k	z	K	Z	k	z	K	Z	k	z	K	Z
11	l	2	L	4	l	2	L	4	l	2	L	4
12	n	3	N	5	n	3	N	5	n	3	N	5

1) New Marking Layout for SC75, implemented at October 2005.

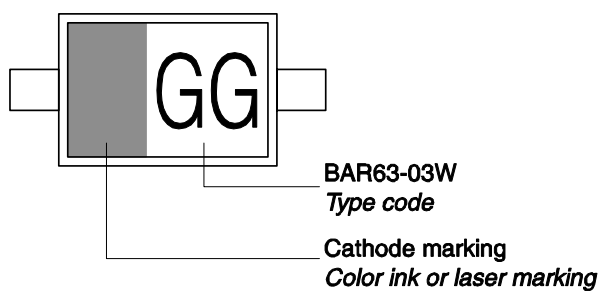
Package Outline



Foot Print

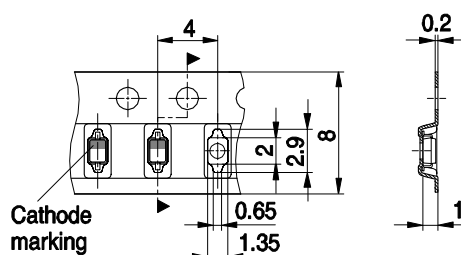


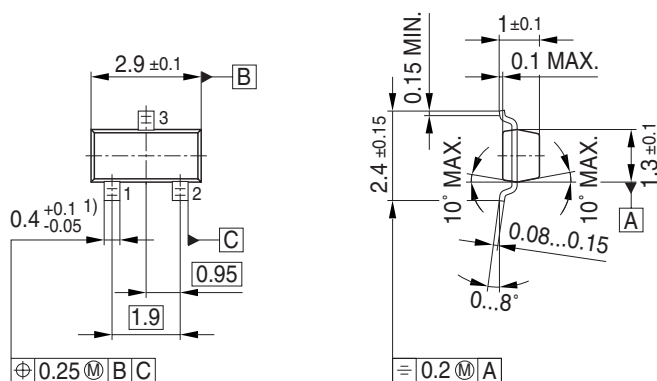
Marking Layout (Example)



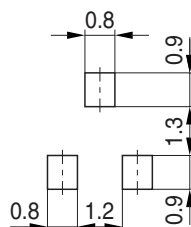
Standard Packing

Reel $\varnothing 180 \text{ mm}$ = 3.000 Pieces/Reel
 Reel $\varnothing 330 \text{ mm}$ = 10.000 Pieces/Reel



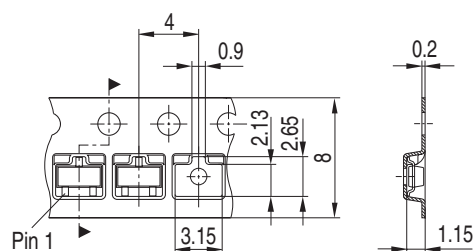


Foot Print

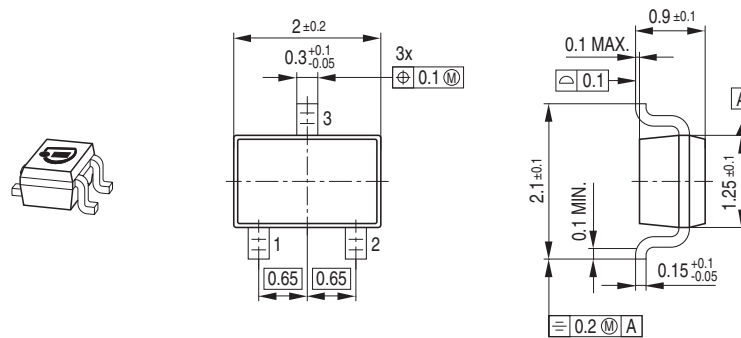


The diagram shows a top-down view of a BCW66 LED package. It is a rectangular component with four pins. The top pin is labeled 'Pin 1'. The package has a central rectangular area containing the text 'EHS' and '2005, June' (Date code (YM)). The Infineon logo is visible in the top right corner. The text 'BCW66' and 'Type code' are located at the bottom right.

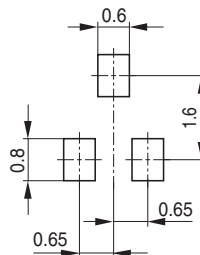
Reel ø180 mm = 3.000 Pieces/Reel
Reel ø330 mm = 10.000 Pieces/Reel



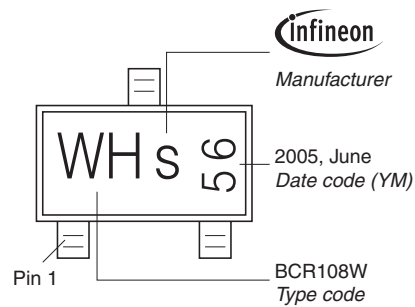
Package Outline



Foot Print

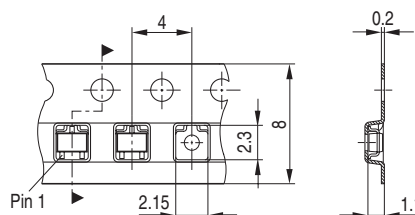


Marking Layout (Example)



Standard Packing

Reel $\varnothing 180$ mm = 3.000 Pieces/Reel
 Reel $\varnothing 330$ mm = 10.000 Pieces/Reel

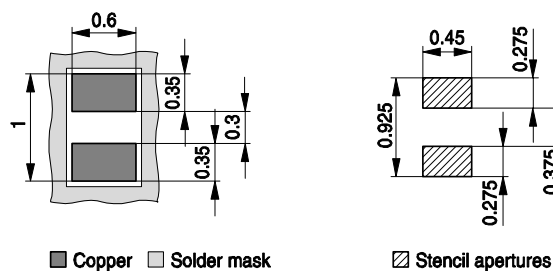


Package Outline

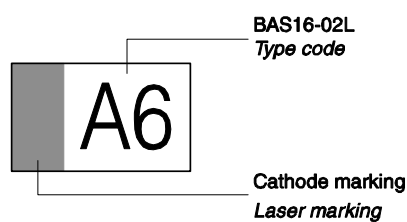


Foot Print

For board assembly information please refer to Infineon website "Packages"

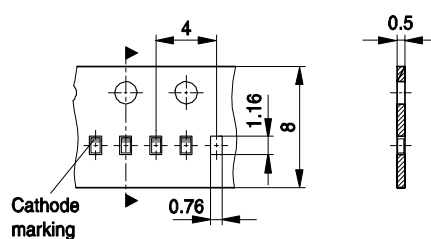


Marking Layout (Example)



Standard Packing

Reel ø180 mm = 15.000 Pieces/Reel
Reel ø330 mm = 50.000 Pieces/Reel (optional)



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